

CLAIMS

1. An electroconductive fine particle,
5 which has a gold coating formed by electroless gold
 plating on the surface of a nickel undercoating,
 the amount of nickel dissolved in a dissolution test
 of the electroconductive fine particle with nitric acid
 being 30 to 100 $\mu\text{g/g}$.
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2. A method of producing the electroconductive fine
particle according to Claim 1,
 wherein the method allows a reducing agent, causing
oxidation reaction on the surface of a nickel undercoating
15 but not causing oxidation reaction on the surface of gold
as deposited metal, to be present on the surface of the
nickel undercoating thereby reduces a gold salt to deposit
gold.
- 20 3. An anisotropic electroconductive material,
 which comprises the electroconductive fine particle
 according to Claim 1 dispersed in a resin binder.